CHIP LEAD FRAMES

ABSTRACT

Chip lead frames are made by disposing a die having terminals on a substrate surface to form a cavity between the die and the substrate and contacts between the terminals and the substrate. A compound is applied to the surface such that the compound enters that cavity and forms a layer on the upper substrate surface. The layer can impart sufficient rigidity to the assembly that the substrate can be etched to produce a lead frame. Also disclosed are devices that include a die, a lead frame, and a continuous network that can form a layer on the lead frame and fill the cavity between the die and the lead frame.

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